



Process Change Notification

PCN Number: PCN-2021-150

PCN Notification Date: 11/02/2021

Initial PCN

Lead Frame Supplier Source change to support the 28L SSOP component material

Dear Customer,

This is an Initial Product Change Notification (PCN) for the Lead Frame supplier source of 28L SSOP component material from ASM (ASM Materials China LTD - CHINA) to PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA).

The described change(s) within this PCN will not take effect (i.e., Ship) any earlier than 60 days from initial PCN notification or the successful completion of the Cirrus Logic qualification, unless a customer agreement has been reached on an earlier implementation of the identified change.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Quality Systems Administrator
Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000



Process Change Notification

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Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:	Lead Frame Supplier Source change to support the 28L SSOP component material				
Customer Contact:	Local Field Sales Representative	Phone:	(512) 851-4000	Dept:	Corporate Quality
Proposed 1st Ship Date:	CY_Q1_2022	Estimated Sample Availability Date:	CY_Q1_2022		
	Assembly Site		Assembly Process		Assembly Materials
	Wafer Fab Site		Wafer Fab Process		Wafer Fab Materials
	Wafer Bump Site		Wafer Bump Process		Wafer Bump Material
	Test Site		Test Process		Design
	Electrical Specification		Mechanical Specification		Part Number
	Packing/Shipping/Labeling	X	Other		Data Sheet
Comments:	Lead Frame Material Supplier Change				

PCN Details	
Description of Change:	
<p>Lead Frame Material Supplier Change:</p> <ul style="list-style-type: none"> • From: ASM (ASM Materials China LTD - CHINA) • To: PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA) <ul style="list-style-type: none"> ○ Note: PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA) is already a qualified lead frame supplier for Cirrus Logic 	
<p>Special Note: Items Remaining the Same</p> <ul style="list-style-type: none"> • POD (Package Outline Drawing) Dimensions Remain the same: All dimensions are within JEDEC MO-150b requirements Reference Appendix A • Lead Frame Material: Remains the same: C194 • Mold Compound Material: Remains the same: Sumitomo EME-G700 • DIE Attach Material: Remains the same: Ablebond 8290 • Moisture Sensitivity Level (MSL): Remains the same: MSL 3 	



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Reason for Change:

Maintain continuity of material supply.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

No anticipated adverse impact to the quality and/or reliability of said product.

Anticipated Impact on Material Declaration:

- No Impact to the Material Declaration Material Declarations or Product Content reports are driven from production data and will be available following the production release.

Product Affected:

Device	Cirrus Logic Part Number
1	CS5464-ISZ
2	CS5464-ISZR
3	CS5467-ISZ
4	CS5467-ISZR
5	CS5464K-ISZ
6	CS5464K-ISZR
7	CS5467K-ISZ
8	CS5467K-ISZR
9	CS5451A-ISZ
10	CS5451A-ISZR

Changes To Product Identification Resulting From This PCN:

There are no changes to the production identification

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The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

Qualification Plan

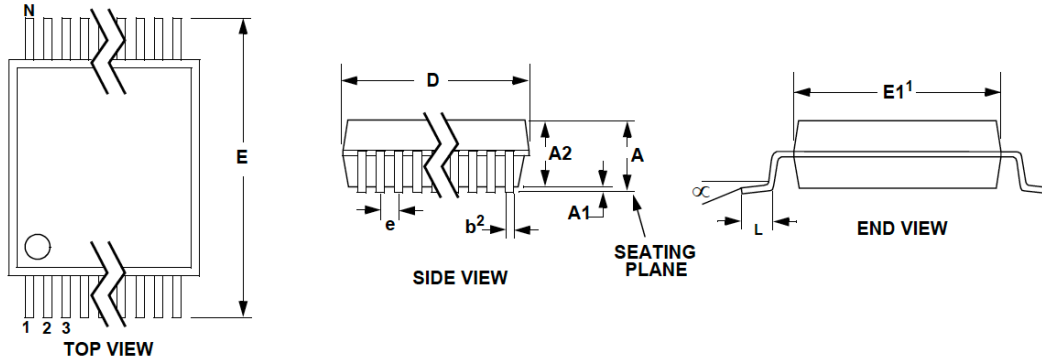
CS5451A-ISZ Qualification: <input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results			
Reliability Test	Standard	Conditions	Sample Size (PASS/FAIL)
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (3 Lots – 5 units / Lot)	# / 15
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (3 Lots – 5 units / Lot)	# / 15
SD (Solderability)	JESD22 B102	245°C / 8 hr steam age before SD (3 Lots – 5 units / Lot)	# / 15
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot – 30 units)	# / 30
PC + TC (MSL3 + Temperature Cycle)	JEDEC J-STD-020A + JESD22 A104	Condition C (-65°C / +150°C) Air to Air (3 Lots – 77 units / Lot) Read Point – 500 Cycles Post Pre-Condition	# / 231
<p>Notes:</p> <ul style="list-style-type: none"> Qualification tests “pass” on zero fails for each test CS5451A-ISZR serves as the Qualification Vehicle for the 28L SSOP Lead Frame Material <p>Reliability Qualification Results:</p> <ul style="list-style-type: none"> Results of the qualification are pending 			



APPENDIX A – POD (PACKAGE OUTLINE DRAWING) DIMENSIONS

*All dimensions are within JEDEC MO-150b requirements

28L SSOP PACKAGE DRAWING



DIM	INCHES			MILLIMETERS			NOTE
	MIN	NOM	MAX	MIN	NOM	MAX	
A	--	--	0.084	--	--	2.13	
A1	0.002	0.006	0.010	0.05	0.15	0.25	
A2	0.064	0.069	0.074	1.62	1.75	1.88	
b	0.009	--	0.015	0.22	--	0.38	2,3
D	0.390	0.4015	0.413	9.90	10.20	10.50	1
E	0.291	0.307	0.323	7.40	7.80	8.20	
E1	0.197	0.209	0.220	5.00	5.30	5.60	1
e	0.022	0.026	0.030	0.55	0.65	0.75	
L	0.025	0.0354	0.041	0.63	0.90	1.03	
α	0°	4°	8°	0°	4°	8°	

JEDEC #: MO-150

Controlling Dimension is Millimeters

- Notes:
1. "D" and "E1" are reference datums and do not include mold flash or protrusions, but do include mold mismatch and are measured at the parting line, mold flash or protrusions shall not exceed 0.20 mm per side.
 2. Dimension "b" does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.13 mm total in excess of "b" dimension at maximum material condition. Dambar intrusion shall not reduce dimension "b" by more than 0.07 mm at least material condition.
 3. These dimensions apply to the flat section of the lead between 0.10 and 0.25 mm from lead tips.